

diameter drill, ensuring rounded curving of the bent pin leads (Fig.1). Check proper pins to mounting hole distance by inserting each transistor onto PCB positioned from the bottom side, as mounting hole of transistor should be aligned with the 3,5 mm diameter mounting hole of the PCB. Readjust pin leads if necessary.

3. Output mosfet transistor T7 (ALF08NP16V5) pin leads should also be bent 90° upwards (in direction to the labeled text print side) by the support of 2,5 mm and 3,5 mm diameter drills. First bent pin leads 2 and 4 around 2,5 mm drill and then bent pin leads 1, 3 and 5 around 3,5 mm drill (Fig.1). In this way all pin leads are at proper distance from transistor's case, which can be visually checked by inserting ALF transistor onto PCB positioned from the bottom side and by observing mounting holes alignment. Readjust pin leads if necessary.

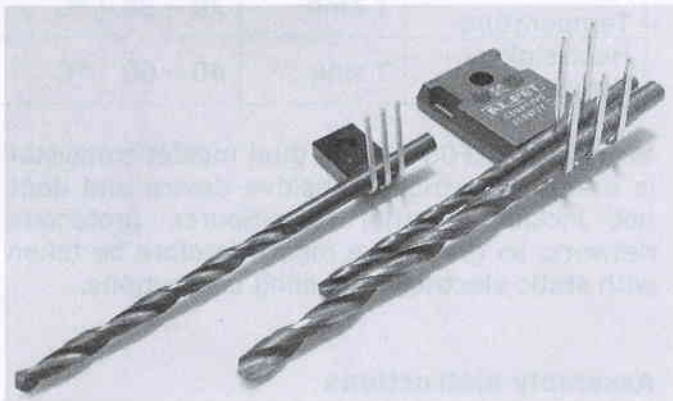


Fig.1 ALF and KSA/KSC pin leads bending

At this phase of assembly soldering of all through hole electronic parts to VSSA PCB is in order. Next six recommended steps to be followed:

1. Insert T1, T2 glued BC pair on the top side of PCB, watch for the correct orientation, since the marked BC560C should be positioned to T1 silk print location. Transistor pair should be leveled down to 4 mm from their plastic cases to the PCB surface distance. Solder all six pin leads from the bottom side, properly heat and dose just the right amount of tin solder to each pin, so the PCB pads are correctly poured on both sides of PCB. Cut off the excessive length of pin leads.
2. Insert VAS transistors T5 (KSA1381) and T6 (KSC3503) onto bottom side of the PCB. The distance from each of these transistors and PCB is assured by 2 mm polyamide spacer, enclosed in the set package, inserted between transistor's upper (labeled text print) side and bottom side of the PCB. Position both transistors in a way that their mounting holes are aligned with mounting holes of the PCB. Both VAS transistors must be firmly secured in a place by M3 x 16 mm bolt and nut, so the soldering is performed on a mechanically fixed device. Use the same method of soldering as described in previous assembly section. Cut off the excessive length of pin leads.
3. Output mosfet transistor T7 (ALF08NP16V5) is next, insert it onto bottom side of the PCB. Position transistor in a way that its mounting hole is aligned with mounting hole of the PCB. Output transistor must be firmly secured in a place by M3 x 16 mm bolt and nut, so the soldering is performed on a mechanically fixed device. Use the same method of soldering as described in the first section of soldering assembly. Cut off the excessive length of pin leads.
4. Now insert and solder C4, C5 (10 μ F, 63 V, MKT, R=15 mm) on their positions on the top side of the PCB. Check that they're aligned inside silk print rectangle. Cut off the excessive length of pin leads.
5. Electrolytic capacitors C2, C3 (2200 μ F, 6,3 V, R=5,0 mm) are next to be soldered. Watch for their correct polarity orientation when positioned on the top side of the PCB. Cut off the excessive length of pin leads.
6. The last four parts to be soldered are electrolytic capacitors C14, C15, C20, C21 (1000 μ F, 50 V, R=7,5 mm). Again watch for their correct polarity orientation when positioned on the top side of the PCB. Cut off the excessive length of pin leads.

At this point VSSA PCB is fully assembled, so now is the time to inspect all soldered through